

LUXBEAM® LLS03

Fine RDL at 3 μm

The advanced-packaging workhorse: 3 μm line and space from a 405 / 375 nm laser, at 102 wafers an hour — redistribution layers, IC substrate and fan-out panel RDL on wafers and panels to 510 $\times$ 515 mm.

Full specification

IMAGING & LAYOUT	
Resolution	3 μm
Light source	405 / 375 nm laser
Throughput — Ø300 mm wafer	102 wph
Throughput — 515 $\times$ 510 mm panel	32 pph
Typical applications	RDL and interposers, IC substrate, CPO, FOPLP fine RDL
Substrate / panel	Wafers, 310 $\times$ 310, 510 $\times$ 515
Segment	Advanced packaging

Figures are for discussion and to be confirmed per application. Throughput depends on resist and energy density — send us both and a field application engineer will verify them for your process.